

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	144	("20020004258" "20020014689" "20020125557" "20020125558" "20020130404" "20030113952" "20030153134" "20040016939" "200400461213" "20060138631" "5222014" "5229960" "5340771" "5373189" "5436203" "5495398" "5550711" "5742127" "5898219" "5899705" "5903049" "5977640" "6025648" "6034875" "6075289" "6118176" "6133626" "6201266" "6201302" "6274930" "6316838" "6333552" "6340846" "6376904" "6388313" "6400007" "6414381" "6424050" "6472732" "6472741" "6489676" "6492726" "6501165" "6538319" "6545365" "6552423" "6570249" "6593647" "6599779" "6611063" "6621169" "6706557" "6737750" "6762488" "6777799" "6787915" "6787916" "6794749" "6828665" "6882057" "6890798" "6900528" "6930378" "6933598" "7034387" "7045887" "7049691" "7053476" "7053477" "7057269" "7061088" "7064426" "7071568" "7081678"). PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/26 21:16
L2	2973	257/678.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/26 21:17
L3	2351	257/686.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/26 21:20
L4	1909	257/777.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/26 21:21
L5	0	((multipackage adj module) and (second with first) and (die with (first adj side)) and (second with substrate) and (interconnected with wire) and ((interconnect adj pads) with (opposite adj edges)) and (solder adj balls)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/26 21:23

## EAST Search History

S1	2736	semiconductor and (package with stacked)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/26 20:52
S2	1275	S1 and (wire adj bond\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:00
S3	467	S2 and (BGA or (ball adj grid adj array))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 09:49
S4	305	S3 and encapsulat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:00
S5	250	S4 and die and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 17:57
S6	103	S5 and (package and stacked).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/06 17:57
S7	34	S6 and (package and stacked and (wire adj bond\$3)).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 09:35
S8	2	("5763913").PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/07 09:35
S9	1534	semiconductor and (package with stacked) and (substrate with (chip or die))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:00
S10	937	S9 and (wire adj bond\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:00

## EAST Search History

S11	428	S10 and (BGA or (ball adj grid adj array))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:35
S12	284	S11 and encapsulat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:35
S13	124	S12 and (package and stacked).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:01
S14	50	S13 and (wire).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:01
S15	10	("20040063246"   "5637916"   "6072122"   "6222265"   "6281581"   "6410981"   "6545365"   "6569712"   "6593647"   "6593662").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/07 14:02
S16	57	("4954878"   "5099306"   "5109320"   "5128831"   "5222014"   "5252857"   "5291061"   "5300801"   "5323060"   "5403784"   "5422435"   "5434745"   "5466627"   "5473814"   "5477082"   "5481134"   "5494841"   "5495398"   "5496775"   "5498902"   "5498905"   "5506756"   "5508565"   "5512765"   "5512780"   "5513076"   "5535101"   "5594275"   "5639696"   "5705858"   "5715144"   "5728606"   "5729440"   "6051878").PN. OR ("6222265").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/07 14:34
S17	486	S9 and ((wire adj bond\$3) with substrate)	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/07 14:34
S18	273	S17 and (BGA or (ball adj grid adj array))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:35
S19	189	S18 and encapsulat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:47

## EAST Search History

S20	106	S19 and heat	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/07 14:57
S21	2	("5373189").PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/07 14:57
S22	46	("5373189").URPN.	USPAT	OR	ON	2004/12/07 14:58
S23	14	(US-5495398-\$ or US-5903049-\$ or US-6222265-\$ or US-6333562-\$ or US-6388313-\$ or US-6410981-\$ or US-6472741-\$ or US-6545365-\$ or US-6555917-\$ or US-6593647-\$ or US-6593662-\$ or US-6605875-\$ or US-6650009-\$ or US-6787915-\$).did.	USPAT	OR	ON	2005/08/08 09:45
S24	5	S23 and (ball adj grid adj array)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 09:45
S25	3249	semiconductor and (package with stacked)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 09:49
S26	1534	S25 and (wire adj bond\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 09:49
S27	579	S26 and (BGA or (ball adj grid adj array))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 09:49
S28	326	S27 and (flip adj chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 09:49
S29	152	S28 and ((flip adj chip) same (ball adj grid adj array))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 09:50

## EAST Search History

S30	668	((chip or die) with substrate) and (substrate with (wire adj bond\$3)) and (((first or second) with substrate) with (solder adj balls))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 12:27
S31	227	S30 and stacked	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/04 12:27
S32	4	("5798564"   "5973393"   "6303997"   "6583503").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/04 12:56
S33	31	("5012323"   "5128831"   "5291061"   "5323060"   "5399898"   "5608262"   "5719440"   "5917242"   "5923090"   "5952725"   "6051878"   "6051886"   "6084308"   "6093938"   "6097098"   "6165815"   "6168973"   "6169329"   "6197613"   "6208018"   "6221691"   "6222265"   "6229158"   "6230400"   "6238949"   "6252305"   "6271601"   "6355977"   "6413797"   "6469370"   "6593662").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/04 12:58
S34	20	("20020004258"   "20020014689"   "20020125557"   "20020125558"   "20020130404"   "5373189"   "5550711"   "5898219"   "6075289"   "6201302"   "6274930"   "6340846"   "6376904"   "6388313"   "6400007"   "6414381"   "6424050"   "6489676"   "6538319"   "6737750").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/04 13:10
S35	20	("20020004258"   "20020014689"   "20020125557"   "20020125558"   "20020130404"   "5373189"   "5550711"   "5898219"   "6075289"   "6201302"   "6274930"   "6340846"   "6376904"   "6388313"   "6400007"   "6414381"   "6424050"   "6489676"   "6538319"   "6737750").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/04 13:10